

**In the claims:**

Please amend claims 1 and 5 as follows:

Sub C  
B1  
1. (Once Amended) A method of forming an electrical device including providing a substrate having a first dielectric upper layer, forming a depression in said first dielectric upper layer, filling said depression with an electrically conductive film having an electrical resistivity and an upper surface that is co-planar with the first dielectric upper layer, said method comprising:

reacting a chemical composition with at least one monolayer of said upper surface to form a passivating layer over the upper surface; and

forming a second dielectric upper layer over said electrically conductive film and said first dielectric upper layer, wherein:

at least an exposed surface of the electrically conductive film is unoxidized; and

said second dielectric upper layer is adhered to said electrically conductive film.

B2  
5. (Twice Amended) The method as defined in Claim 1, wherein the passivating layer chemically protects the first one to one thousand atomic lattice layers of the upper surface.